

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIDETO TATENO	02/04/2016
DAISUKE HARA	02/04/2016
RECEIVING PARTY DATA	
Name:	HITACHI KOKUSAI ELECTRIC INC.
Street Address:	14-1, SOTOKANDA 4-CHOME, CHIYODA-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	101-8980
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29555040
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	(312) 577-7000
Email:	knugent@fitcheven.com
Correspondent Name:	FITCH, EVEN, TABIN & FLANNERY, LLP
Address Line 1:	120 SOUTH LASALLE STREET, SUITE 1600
Address Line 4:	CHICAGO, ILLINOIS 60603-3406
ATTORNEY DOCKET NUMBER:	20372-138166-US
NAME OF SUBMITTER:	ALAN E. SCHIAVELLI
SIGNATURE:	/Alan E. Schiavelli/
DATE SIGNED:	02/18/2016
Total Attachments: 1	
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ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi Kokusai Electric Inc. a corporation organized under the laws of Japan, located at 14-1, Sotokanda 4-chome, Chiyoda-ku, TOKYO 101-8980, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi Kokusai Electric Inc. its successor and assigns, all my right, title and interest, in and for the United States of America, in and to

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invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi Kokusai Electric Inc. its successor, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi Kokusai Electric Inc.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u><i>Hidetotatano</i></u> Hideto TATENO	<u>Feb. 4, 2016</u>
2) <u><i>Daisuke Hara</i></u> Daisuke HARA	<u>Feb. 4, 2016</u>
3) _____	_____
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____